Load Transient Response Testing for Voltage Regulators

Practical Considerations for Testing and Evaluating Results

Jim Williams

INTRODUCTION

Semiconductor memory, card readers, microprocessors, disc drives, piezoelectric devices and digitally based systems furnish transient loads that a voltage regulator must service. Ideally, regulator output is invariant during a load transient. In practice, some variation is encountered and becomes problematic if allowable operating voltage tolerances are exceeded. This mandates testing the regulator and its associated support components to verify desired performance under transient loading conditions. Various methods are employable to generate transient loads, allowing observation of regulator response.

Basic Load Transient Generator

Figure 1 diagrams a conceptual load transient generator. The regulator under test drives DC and switched resistive loads, which may be variable. The switched current and output voltage are monitored, permitting comparison of the nominally stable output voltage versus load current under static and dynamic conditions. The switched current is either on or off; there is no controllable linear region.

Figure 2 is a practical implementation of the load transient generator. The voltage regulator under test is augmented by capacitors which provide an energy reservoir, similar to a mechanical flywheel, to aid transient response. The size, composition and location of these capacitors, particularly $C_{\text{OUT}}$, has a pronounced effect on transient response and overall regulator stability.\(^1\) Circuit operation is straightforward. The input pulse triggers the LTC1693 FET driver to switch Q1, generating a transient load current out of the

An oscilloscope monitors the instantaneous load voltage and, via a “clip-on” wideband probe, current. The circuit’s load transient generating capabilities are evaluated in Figure 3 by substituting an extraordinarily low impedance power source for the regulator. The combination of a high capacity power supply, low impedance connections and generous bypassing maintains low impedance across frequency. Figure 4 shows Figure 3 responding to the LTC1693-1 FET driver (Trace A) by cleanly switching 1A in 15ns (Trace B). Such speed is useful for simulating many loads but has restricted versatility. Although fast, the circuit cannot emulate loads between the minimum and maximum currents.

Operating point. Q1’s current assumes a value dependent on the control input voltage and the current sense resistor over a very wide bandwidth. Note that once A1 biases to Q1’s conductance threshold, small variations in A1’s output result in large current changes in Q1’s channel. As such, large output excursions are not required from A1; its small signal bandwidth is the fundamental speed limitation. Within this restriction, Q1’s current waveform is identically shaped to A1’s control input voltage, allowing linear control of load current. This versatile capability permits a wide variety of simulated loads.

**FET Based Circuit**

Figure 6, a practical incarnation of a FET based closed loop load transient generator, includes DC bias and waveform inputs. A1 must drive Q1’s high capacitance gate at high frequency, necessitating high peak A1 output currents and attention to feedback loop compensation. A1, a 60MHz current feedback amplifier, has an output current capacity exceeding 1A. Maintaining stability and waveform fidelity at high frequency while driving Q1’s gate capacitance necessitates settable gate drive peaking components, a damper network, feedback trimming and loop peaking adjustments. A DC trim, also required, is made first. With no input applied, trim the “1mV adjust” for 1mV DC at Q1’s source. The AC trims are made utilizing Figure 7’s arrangement. Similar to Figure 3, this “brick wall” regulated source provides minimal ripple and sag when step loaded by the load transient generator. Apply the inputs shown and trim the gate drive, feedback and loop peaking adjustments for the cleanest, square cornered response on the oscilloscope’s current probe equipped channel.
Bipolar Transistor Based Circuit

Figure 8 considerably simplifies the previous circuit's loop dynamics and eliminates all AC trims. The major trade-off is a 2x speed reduction. The circuit is similar to Figure 6, except that Q1 is a bipolar transistor. The bipolar's greatly reduced input capacitance allows A1 to drive a more benign load. This permits a lower output current amplifier and eliminates the dynamic trims required to accommodate Figure 6's FET gate capacitance. The sole trim is the "1mV adjust" which is accomplished as described before. Aside from the 2x speed reduction the bipolar transistor also introduces a 1% output current error due to its base current.

Q2 is added to prevent excessive Q1 base current when the regulator supply is not present. The diode prevents reverse base bias under any circumstances.

Closed Loop Circuit Performance

Figures 9 and 10 show the two wideband circuits' operation. The FET based circuit (Figure 9) only requires a 50mV A1 swing (Trace A) to enforce Trace B's flat-topped current pulse with 50ns edges through Q1. Figure 10 details the bipolar transistor based circuit's performance. Trace A, taken at Q1's base, rises less than 100mV causing Trace B's clean 1A current conduction through Q1. This circuit's 100ns edges, about 2x slower than the more complex FET based version, are still fast enough for most practical transient load testing.
Load Transient Testing

The previously discussed circuits permit rapid and thorough voltage regulator load transient testing. Figure 11 uses Figure 6’s circuit to evaluate an LT1963A linear regulator. Figure 12 shows regulator response (Trace B) to Trace A’s asymmetrically edged input pulse. The ramped leading edge, within the LT1963A’s bandwidth, results in Trace B’s smooth 10mVP-P excursion. The fast trailing edge, well outside LT1963A passband, causes Trace B’s abrupt disruption. C\textsubscript{OUT} cannot supply enough current to maintain output level and a 75mVP-P spike results before the regulator resumes control. In Figure 13, a 500mA peak-to-peak 500kHz noise load, emulating a multitude of incoherent loads, feeds the regulator in Trace A. This is within regulator bandwidth and only 6mV\textsubscript{P-P} of disturbance appears in Trace B, the regulator output. Figure 14 maintains the same conditions, except that noise bandwidth is increased to 5MHz. Regulator bandwidth is exceeded, resulting in over 50mVP-P error, an 8x increase.

Figure 15 shows what happens when a 0.2A DC biased, swept DC-5MHz, 0.35A load is presented to the regulator. The regulator’s rising output impedance versus frequency results in ascending error as frequency scales. This information allows determination of regulator output impedance versus frequency.
Figure 11. Closed Loop Load Tester Shown with LT1963A Regulator. Load Testing for a Variety of Current Load Waveshapes is Possible

Figure 12. Figure 11 Responds (Trace B) to Asymmetrically Edged Pulse Input (Trace A). Ramped Leading Edge, Within LT1963A Bandwidth, Results in Trace B’s Smooth 10mVp-p Excursion. Fast Trailing Edge, Outside LT1963A Bandwidth, Causes Trace B’s Abrupt 75mVp-p Disruption. Traces Latter Portion Intensified for Photographic Clarity

Figure 13. 500mA-p-p, 500kHz Noise Load (Trace A), Within Regulator Bandpass, Produces Only 6mV Artifacts at Trace B’s Regulator Output

Figure 14. Same Conditions as Figure 13, Except Noise Bandwidth Increased to 5MHz. Regulator Bandwidth is Exceeded, Resulting in 50mVp-p Output Error

Figure 15. Swept DC – 5MHz, 0.35A Load (On 0.2ADC) Results in Above Regulator Response. Regulator Output Impedance Rises with Frequency, Causing Corresponding Ascending Output Error
Capacitor’s Role in Regulator Response

The regulator employs capacitors at its input (C_IN) and output (C_OUT) to augment its high frequency response. The capacitor’s dielectric, value and location greatly influence regulator characteristics and must be quite carefully considered. C_OUT dominates the regulator’s dynamic response; C_IN is much less critical, so long as it does not discharge below the regulator’s dropout point. Figure 16 shows a typical regulator circuit and emphasizes C_OUT and its parasitics. Parasitic inductance and resistance limit capacitor effectiveness at frequency. The capacitor’s dielectric and value significantly influence load step response. A “hidden” parasitic, impedance build-up in regulator output trace runs, also influences regulation characteristics, although its effects can be minimized by remote sensing (shown) and distributed capacitive bypassing.

Figure 17 shows Figure 16’s circuit responding (Trace B) to a 0.5A load step biased on 0.1A DC (Trace A) with C_IN = C_OUT = 10µF. The low loss capacitors employed result in Trace B’s well controlled output. Figure 18 greatly expands the horizontal time scale to investigate high frequency behavior. Regulator output deviation (Trace B) is smooth, with no abrupt discontinuities. Figure 19 runs the same test as Figure 17 using an output capacitor claimed as “equivalent” to the one employed in Figure 17. At 10µs/division things seem very similar, but Figure 20 indicates problems. This photo, taken at the same higher sweep speed as Figure 18, reveals the “equivalent” capacitor to have a 2x amplitude error versus Figure 18, higher frequency content and

Note 3. See Appendices A and B for extended discussion of these concerns.
resonances. Figure 21 substitutes a very lossy 10µF unit for C_{OUT}. This capacitor allows a 400mV excursion (note Trace B’s vertical scale change), >4x Figure 18’s amount. Conversely, Figure 22 increases C_{OUT} to a low loss 33µF type, decreasing Trace B’s output response transient by 40% versus Figure 18. Figure 23’s further increase, to a low loss 330µF capacitor, keeps transients inside 20mV, 4x lower than Figure 18’s 10µF value.

The lesson from the preceding study is clear. Capacitor value and dielectric quality have a pronounced effect on transient load response. Try before specifying!

**Load Transient Risetime versus Regulator Response**

The closed loop load transient generator also allows investigating load transient risetime on regulation at high speed. Figure 24 shows Figure 16’s circuit (C_{IN} = C_{OUT} = 10µF) responding to a 0.5A, 100ns risetime step on a 0.1A DC load (Trace A). Response decay (Trace B) peaks at 75mV with some following aberrations. Decreasing Trace A’s load step risetime (Figure 25) almost doubles Trace B’s response error, with attendant enlarged following aberrations. This indicates increased regulator error at higher frequency.

All regulators present increasing error with frequency, some more so than others. A slow load transient can unfairly make a poor regulator look good. Transient load testing that does not indicate some response outside regulator bandwidth is suspect.

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**Note 4.** Always specify components according to observed performance, never to salesman’s claims.
A Practical Example – Intel P30 Embedded Memory Voltage Regulator

A good example of the importance of voltage regulator load step performance is furnished by the Intel P30 embedded memory. This memory requires a 1.8V supply, typically regulated down from +3V. Although current requirements are relatively modest, supply tolerances are tight. Figure 26’s error budget shows only 0.1V allowable excursion from 1.8V, including all DC and dynamic errors. The LTC1844-1.8 regulator has a 1.75% initial tolerance (31.5mV), leaving only a 68.5mV dynamic error allowance. Figure 27 is the test circuit. Memory control line movement causes 50mA load transients, necessitating attention to capacitor selection.\(^5\) If the regulator is close to the power source \(C_{\text{IN}}\) is optional. If not, use a good grade 1\(\mu\)F capacitor for \(C_{\text{IN}}\). \(C_{\text{OUT}}\) is a low loss 1\(\mu\)F type. In all other respects the circuit appears deceptively routine. A load transient generator provides Figure 28’s output load test step (Trace A).\(^6\) Trace B’s regulator response shows just 30mV peaks, >2x better than required. Increasing \(C_{\text{OUT}}\) to 10\(\mu\)F, in Figure 29, reduces peak output error to 12mV, almost 6x better than specification. However, a poor grade 10\(\mu\)F (or 1\(\mu\)F, for that matter) capacitor produces Figure 30’s unwelcome surprise. Severe peaking error on both edges occurs (Trace B’s latter portion has been intensified to aid photograph clarity) with 100mV observable on the negative going edge. This is well outside the error budget and would cause unreliable memory operation.

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>LIMITS</th>
</tr>
</thead>
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<tr>
<td>Intel Specified Supply Limits</td>
<td>(1.8V \pm 0.1V)</td>
</tr>
<tr>
<td>LTC1844 Regulator Initial Accuracy</td>
<td>(\pm 1.75% \pm 31.5mV)</td>
</tr>
<tr>
<td>Dynamic Error Allowance</td>
<td>(\pm 68.5mV)</td>
</tr>
</tbody>
</table>

Figure 26. Error Budget for Intel P30 Embedded Memory Voltage Regulator. 1.8V Supply Must Remain Within \(\pm 0.1V\) Tolerance, Including All Static and Dynamic Errors

Figure 27. P30 Embedded Memory \(V_{\text{CC}}\) Regulator Must Maintain \(\pm 0.1V\) Error Band. Control Line Movement Causes 50mA Load Steps, Necessitating Attention to \(C_{\text{OUT}}\) Selection

Note 5. The LTC1844-1.8’s noise bypass pin (“BYP”) is used with an optional external capacitor to achieve extremely low output noise. It is not required for this application and is left unconnected.

Note 6. Figure 8’s circuit was used for this test, with Q1’s emitter current shunt changed to 1\(\Omega\).
3. Williams, Jim, “Minimizing Switching Residue in Linear

APPENDIX A

Capacitor Parasitic Effects on Load Transient Response

Tony Bonte

Large load current changes are typical of digital systems. The load current step contains higher order frequency components that the output decoupling network must handle until the regulator throttles to the load current level. Capacitors are not ideal elements and contain parasitic resistance and inductance. These parasitic elements dominate the change in output voltage at the beginning of a transient load step change. The ESR (equivalent series resistance) of the output capacitors produces an instantaneous step in output voltage. \(\Delta V = \Delta I \cdot \text{ESR}\). The ESL (equivalent series inductance) of the output capacitors produces a droop proportional to the rate of change of output current \(V = L \cdot \frac{\Delta I}{\Delta t}\). The output capacitance produces a change in output voltage proportional to the time until the regulator can respond \(\Delta V = \Delta t \cdot \Delta I / C\). These transient effects are illustrated in Figure A1.

The use of capacitors with low ESR, low ESL, and good high frequency characteristics is critical in meeting the output load voltage tolerances. These requirements dictate high quality, surface mount tantalum, ceramic or organic electrolyte capacitors. The capacitor’s location is critical to transient response performance. Place the capacitor as close as possible to the regulator pins and keep supply line traces and planes at low impedance, bypassing individual loads as necessary. If the regulator has remote sensing capability, consider sensing at the heaviest load point.

Strictly speaking, the above are not the only time related terms that can influence regulator settling. Figure A2 lists 7 different terms, occurring over 9 decades of time, that can potentially influence regulation. The regulator IC must be carefully designed to minimize regulator loop and thermal error contributions.

Figure A1. Parasitic Resistance, Inductance and Finite Capacitance Combine with Regulator Gain-Bandwidth Limitations to Form Load Step Response. Capacitors Equivalent Series Resistance (ESR) and Inductance (ESL) Dominate Initial Response; Capacitor Value and Regulator Gain-Bandwidth Determine Responses Latter Profile

Figure A2. Time Constants Potentially Influencing Regulator Settling Time After a Load Step are Electrical and Thermal. Effects Span Over 9 Decades
Application Note 104

APPENDIX B

Output Capacitors and Loop Stability

Dennis O’Neill

Editorial Note: The following text, excerpted from the LT1963A datasheet, concerns the output capacitor’s relationship to transient response. Although originally prepared for LT1963A application, it is generalizable to most regulators and is presented here for reader convenience.

A voltage regulator is a feedback circuit. Like any feedback circuit, frequency compensation is needed to make it stable. For the LT1963A, the frequency compensation is both internal and external – the output capacitor. The size of the output capacitor, the type of the output capacitor, and the ESR of the particular output capacitor all affect the stability.

In addition to stability, the output capacitor also affects the high frequency transient response. The regulator loop has finite bandwidth. For high frequency transient loads recovery from a transient is a combination of the output capacitor and the bandwidth of the regulator. The LT1963A was designed to be easy to use and accept a wide variety of output capacitors. However, the frequency compensation is affected by the output capacitor and optimum frequency stability may require some ESR, especially with ceramic capacitors.

For ease of use, low ESR polyan tantalum capacitors (POSCAP) are a good choice for both the transient response and stability of the regulator. These capacitors have intrinsic ESR that improves the stability. Ceramic capacitors have extremely low ESR, and while they are a good choice in many cases, placing a small series resistance element will sometimes achieve optimum stability and minimize ringing. In all cases, a minimum of 10µF is required while the maximum ESR allowable is 3Ω.

The place where ESR is most helpful with ceramics is low output voltage. At low output voltages, below 2.5V, some ESR helps the stability when ceramic output capacitors are used. Also, some ESR allows a smaller capacitor value to be used. When small signal ringing occurs with ceramics due to insufficient ESR, adding ESR or increasing the capacitor value improves the stability and reduces the ringing. Figure B1 gives some recommended values of ESR to minimize ringing caused by fast, hard current transitions.

Figures B2 through B7 show the effect of ESR on the transient response of the regulator. These scope photos show the transient response for the LT1963A at three different output voltages with various capacitors and various values of ESR. The output load conditions are the same for all traces. In all cases there is a DC load of 500mA. The load steps up to 1A at the first transition and steps back to 500mA at the second transition.

At the worst case point of 1.2VOUT with 10µF COUT (Figure B2), a minimum amount of ESR is required. While 20mΩ is enough to eliminate most of the ringing, a value closer to 50mΩ provides a more optimum response. At 2.5V output with 10µF COUT (Figure B3) the output rings at the transitions with 0Ω ESR but still settles to within 10mV in 20µs after the 0.5A load step. Once again a small value of ESR will provide a more optimum response.

At 5VOUT with 10µF COUT (Figure B4) the response is well damped with 0Ω ESR.

With a COUT of 100µF at 0Ω ESR and an output of 1.2V (Figure B5), the output rings although the amplitude is only 20mVp-p. With COUT of 100µF it takes only 5mΩ to 20mΩ of ESR to provide good damping at 1.2V output. Performance at 2.5V and 5V output with 100µFCOUT shows similar characteristics to the 10µF case (see Figures B6 to B7). At 2.5VOUT 5mΩ to 20mΩ can improve transient response. At 5VOUT the response is well damped with 0Ω ESR.

Capacitor types with inherently higher ESR can be combined with 0mΩ ESR ceramic capacitors to achieve both good high frequency bypassing and fast settling time. Figure B8 illustrates the improvement in transient response that can be seen when a parallel combination of ceramic and

<table>
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<th>VOUT</th>
<th>10µF</th>
<th>22µF</th>
<th>47µF</th>
<th>100µF</th>
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<td>1.2V</td>
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<td>15mΩ</td>
<td>10mΩ</td>
<td>5mΩ</td>
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<tr>
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<td>10mΩ</td>
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<td>2.5V</td>
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<td>5mΩ</td>
<td>5mΩ</td>
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<td>3.3V</td>
<td>0mΩ</td>
<td>0mΩ</td>
<td>0mΩ</td>
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<tr>
<td>≥ 5V</td>
<td>0mΩ</td>
<td>0mΩ</td>
<td>0mΩ</td>
<td>0mΩ</td>
</tr>
</tbody>
</table>

Figure B1. Capacitor Minimum ESR
**Application Note 104**

**Figure B2**

- **VOUT = 1.2V**
- **IOUT = 500mA WITH 500mA PULSE**
- **COUT = 10µF**

**Figure B3**

- **VOUT = 2.5V**
- **IOUT = 500mA WITH 500mA PULSE**
- **COUT = 10µF**

**Figure B4**

- **VOUT = 5V**
- **IOUT = 500mA WITH 500mA PULSE**
- **COUT = 10µF**

**Figure B5**

- **VOUT = 1.2V**
- **IOUT = 500mA WITH 500mA PULSE**
- **COUT = 100µF**

**Figure B6**

- **VOUT = 2.5V**
- **IOUT = 500mA WITH 500mA PULSE**
- **COUT = 100µF**

**Figure B7**

- **VOUT = 5V**
- **IOUT = 500mA WITH 500mA PULSE**
- **COUT = 100µF**

**Figure B8**

- **VOUT = 1.2V**
- **IOUT = 500mA WITH 500mA PULSE**
- **COUT =**
  - A = 10µF CERAMIC
  - B = 10µF CERAMIC II 22µF/45mΩ POLY
  - C = 10µF CERAMIC II 100µF/35mΩ POLY
POSCAP capacitors are used. The output voltage is at the worst case value of 1.2V. Trace A with a 10µF ceramic output capacitor, shows significant ringing with a peak amplitude of 25mV. For Trace B, a 22µF/45mΩ POSCAP is added in parallel with the 10µF ceramic. The output is well damped and settles to within 10mV in less than 20µs.

For Trace C, a 100µF/35mΩ POSCAP is connected in parallel with the 10µF ceramic capacitor. In this case the peak output deviation is less than 20mV and the output settles in about 10µs. For improved transient response the value of the bulk capacitor (tantalum or aluminum electrolytic) should be greater than twice the value of the ceramic capacitor.

**Tantalum and Polytantalum Capacitors**

There is a variety of tantalum capacitor types available, with a wide range of ESR specifications. Older types have ESR specifications in the hundreds of mΩ to several Ohms. Some newer types of polytantalum with multi-electrodes have maximum ESR specifications as low as 5mΩ. In general the lower the ESR specification, the larger the size and the higher the price. Polytantalum capacitors have better surge capability than older types and generally lower ESR. Some types such as the Sanyo TPE and TPB series have ESR specifications in the 20mΩ to 50mΩ range, which provide near optimum transient response.

**Aluminum Electrolytic Capacitors**

Aluminum electrolytic capacitors can also be used with the LT1963A. These capacitors can also be used in conjunction with ceramic capacitors. These tend to be the cheapest and lowest performance type of capacitors. Care must be used in selecting these capacitors as some types can have ESR which can easily exceed the 3Ω maximum value.

**Ceramic Capacitors**

Extra consideration must be given to the use of ceramic capacitors. Ceramic capacitors are manufactured with a variety of dielectrics, each with different behavior over temperature and applied voltage. The most common dielectrics used are Z5U, Y5V, X5R and X7R. The Z5U and Y5V dielectrics are good for providing high capacitances in a small package, but exhibit strong voltage and temperature coefficients as shown in Figures B9 and B10. When used with a 5V regulator, a 10µF Y5V capacitor can exhibit an effective value as low as 1µF to 2µF over the operating temperature range. The X5R and X7R dielectrics result in more stable characteristics and are more suitable for use as the output capacitor. The X7R type has better stability across temperature, while the X5R is less expensive and is available in higher values.
Voltage and temperature coefficients are not the only sources of problems. Some ceramic capacitors have a piezoelectric response. A piezoelectric device generates voltage across its terminals due to mechanical stress, similar to the way a piezoelectric accelerometer or microphone works. For a ceramic capacitor the stress can be induced by vibrations in the system or thermal transients.

“FREE” Resistance with PC Traces

The resistance values shown in Figure B11 can easily be made using a small section of PC trace in series with the output capacitor. The wide range of non-critical ESR makes it easy to use PC trace. The trace width should be sized to handle the RMS ripple current associated with the load. The output capacitor only sources or sinks current for a few microseconds during fast output current transitions. There is no DC current in the output capacitor. Worst case ripple current will occur if the output load is a high frequency (>100kHz) square wave with a high peak value and fast edges (<1µs). Measured RMS value for this case is 0.5 times the peak-to-peak current change. Slower edges or lower frequency will significantly reduce the RMS ripple current in the capacitor.

This resistor should be made using one of the inner layers of the PC board which are well defined. The resistivity is determined primarily by the sheet resistance of the copper laminate with no additional plating steps. Figure B11 gives some sizes for 0.75A RMS current for various copper thicknesses. More detailed information regarding resistors made from PC traces can be found in Application Note 69, Appendix A.

<table>
<thead>
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<th>Width</th>
<th>10mΩ</th>
<th>20mΩ</th>
<th>30mΩ</th>
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<td></td>
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<tr>
<td></td>
<td>0.102&quot; (2.6mm)</td>
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<td>0.006&quot; (0.15mm)</td>
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<tr>
<td></td>
<td>0.110&quot; (2.8mm)</td>
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<tr>
<td>2.0oz Cu</td>
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<tr>
<td></td>
<td>0.224&quot; (5.7mm)</td>
<td>0.450&quot; (11.4mm)</td>
<td>0.670&quot; (17mm)</td>
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Figure B11. PC Trace Resistors
Probing Considerations for Load Transient Response Measurements

Signals of interest in load transient response studies occur within a bandwidth of about 25MHz ($t_{\text{RISE}} = 14\text{ns}$). This is a modest speed range but probing technique requires some care for high fidelity measurement. Load current is measured with a DC stabilized (Hall Effect based) “clip on” current probe such as the Tektronix P-6042 or AM503. The conductor loop placed in the probe jaws should encompass the smallest possible area to minimize introduced parasitic inductance, which can degrade measurement. At higher speeds, grounding the probe case may slightly decrease measurement aberrations, but this is usually a small effect.

Voltage measurement, typically AC-coupled and in the 10mV to 250mV range, is best accomplished with Figure C1’s arrangement. The measured voltage is fed to a BNC fixtured 50Ω back terminated cable, which drives the oscilloscope via a DC blocking capacitor and a 50Ω termination.

The back termination is strict practice, enforcing a true 50Ω signal path. Practically, if its $\div 2$ attenuation presents problems, it can usually be eliminated with only minor signal degradation in the 25MHz measurement passband. The termination at the oscilloscope end is not negotiable. Figure C2 shows a typical observed load transient with no back termination but 50Ω at the oscilloscope. The presentation is clean and well defined. In C3, the cable’s 50Ω termination is removed, causing a distorted leading edge, ill-defined peaking and pronounced post-event ringing. Even at relatively modest frequencies the cable displays unterminated transmission line characteristics, resulting in signal distortion.

In theory, a 1x scope probe using a probe-tip coaxial connection could replace the above but such probes usually have bandwidth limitations of 10MHz to 20MHz. Conversely, a 10x probe is wideband, but oscilloscope vertical sensitivity must accommodate the introduced attenuation.

Figure C1. Coaxial Load Transient Voltage Measurement Path Promotes Observed Signal Fidelity. 50Ω Back Termination May Be Removed with Minimal Impact on 25MHz Signal Path Integrity. 50Ω Termination at Oscilloscope Cannot Be Deleted

Figure C2. Typical High Speed Transient Observed Through Figure C1’s Measurement Path. Presentation is Clean and Well Defined

Figure C3. Figure C2’s Transient Measured with 50Ω Oscilloscope Termination Removed. Waveform Distortion and Post-Event Ringing Result
A Trimless Closed Loop Transient Load Tester

Text Figure 8’s circuit is attractive because it eliminates the FET based design’s AC trims. It does, however, retain the DC trim. Figure D1 trades circuit complexity to eliminate the DC trim. Operation is similar to text Figure 8’s circuit except that A2 appears. This amplifier replaces the DC trim by measuring the circuits DC input, comparing it to Q1’s emitter DC level and controlling A1’s positive input to stabilize the circuit. High frequency signals are filtered at A1’s inputs and do not corrupt A1’s stabilizing action. A useful way to consider circuit operation is that A2 will balance its inputs, and hence the circuit’s input and output, regardless of A1’s DC input errors. DC current bias is set to any desired point by a variable reference source directed to A2’s positive input. This network’s resistors are arranged for a minimum load current of 10mA, avoiding loop disruption for currents near zero.

![Figure D1. A2 Feedback Controls A1’s DC Errors, Eliminating Text Figure 8’s Trim. Filtering Restricts A2’s Response to DC and Low Frequency](image-url)
Methinks the load doth protest too much.

(with apologies to Wm. Shakespeare)